Company: **UC Berkeley** Date: 10/20/2017

Contact Name: **Taehwan Kim** Customer PO: **Click here to enter text.**

Phone: **5102953549** ACI #: **Click here to enter text.**

Email: **taehwan@berkeley.edu** Turn Time: Normal (10 business days)

Expedite (additional charge)

Product Name/Description: **DODOS TIA** 1st Article Required (additional charge)

Quantity of Die to be Packaged: **10**

Desired Package Lead Count: **39**

Package Supplied By: Select one Lid Supplied By: Select one

Die Attach: 80Au/20Sn Epoxy Non-conductive Epoxy Conductive Advotech DiscretionFlip Chip:Other: **Click here to enter text.** (Bump Alloy: **Click here to enter text.**)

Die Size (L x W x H): **2000x1000um**

Die pad width & pitch (center to center): Width: **94um** Pitch: **188um**

Wire Bonding Diagram: Provided Will Provide Later

*(Please send now if available. Diagram can be supplied later if this is a budgetary quote)*

Wire Count: **Click here to enter text.**

Bond Wire Type: Au AlSi Cu Ag Advotech Discretion

Bond Wire Size: 0.7 0.8 0.9 1.0 1.2 1.3 1.5 2.0mil

Advotech Discretion

Bond Type: Ball Bond Wedge Bond Ribbon Bond Stud Bump

Package: Ceramic Plastic LCC QFN PGA DIP

Other: **Click here to enter text.**

PCB/Substrate – Dimensions **Click here to enter text.**

Prepopulated? NO or YES – If yes, Single Sided Double Sided

Package Sealing Preference: Glob-Top Removable Lid (taped) Hermetic

**Clear Black**

Reliability Testing: Wire Pull Die Shear Stud Bump Shear Bond Shear

X-Ray No Testing Required

Should the testing be: Destructive Non-destructive with specified limits

Test Requirements: **Click here to enter text.**

Electrical Testing: Test Parameters: **Click here to enter text.**

None Requested

Special Instructions and considerations: (Pin Orientation, Part #, heat sensitivity, DOD requirements):